勝 特 力 材 料 886-3-5753170 胜特力电子(上海) 86-21-34970699 胜特力电子(深圳) 86-755-83298787 Http://www.100y.com.tw



※RoHS compliant

ORDERING PROCEDURE **BGA/LGA** - □ □ □ P - □ . □ □ - □ □ - Design NO. Pin Count

SPECIFICATIONS

- Socket Series

Contact resistance: Initial $500 \text{m} \Omega$ (PS) / $200 \text{m} \Omega$ (BPS)(At 10 mA)INITIAL

Maximum voltage: AC300V RMS (for 1 minute) Insulation resistance: 1,000 M Ω or higher (At DC 500V)

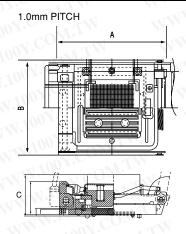
Rated current: 0.5A

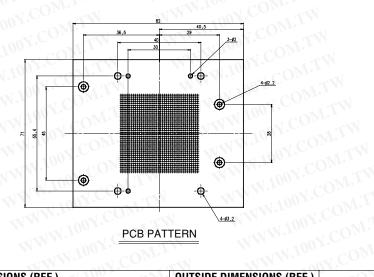
Insertion: Min 10,000 times (mechanical)

MATERIAL

Body: PEI, PES

Contact: BeCu, Au plating (Ni-base)





BGA-1444P SERIES (1.0mm PITCH)

PART NO.	API	PLICABLE	IC DIMENSIONS (REF.)	COM	OUTSIDE	DIMENSIO	NS (REF.)	-1 CON
PART NO.	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	Α	В	C	REMARKS
BGA-955(1444P)-1.0-01	33×33	31	Depopulated	955	of CON				N CO
BGA-1156(1444P)-1.0-**	35×35	34	Fully Aray	1156	1.0	71	82	29.4	100 -
BGA-1444P-1.0-**	40×40	38	Fully Aray	1444	V CO				LOV.U

⁻Max.40×40mm Package can be accommodated

BGA-576P SERIES (0.65mm PITCH)

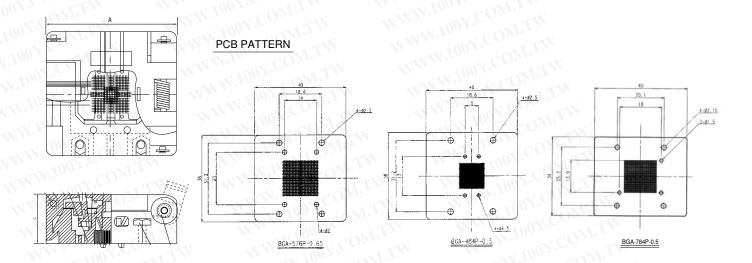
PART NO.	API	PLICABLE	IC DIMENSIONS (REF.)	A OUT!	OUTSIDE	DIMENSIO	NS (REF.)	-1100
PANI NU.	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	COA	В	C	REMARKS
BGA-100(576P)-0.65-16	7×7	10	Fully Aray	100	1007	Mo	1.4	77	- XX 101
BGA-174(576P)-0.65-17	10×10	14	Depopulated	174	1.5	COn	TXV.	11	Maria
BGA-204(576P)-0.65-10	12×12	18	Depopulated	204	$\propto 100$	MOD			
BGA-188(576P)-0.65-11	13×13	18	Depopulated	188	0.65	40	38	15	
BGA-232(576P)-0.65-04	14×14	20	Depopulated	232	TV 10	001	17.7		
BGA-324(576P)-0.65-07	16×16	22	Depopulated	324	N				
BGA-304(576P)-0.65-14	16×16	23	Depopulated	304	- W.V.				
Max.16×16mm Package	can be accomr	nodated							
23									

⁻Max.16×16mm Package can be accommodated WWW.100Y.COM.TW

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Applicable IC/BGA · LGA

Clam Shell Surface Mount Type Socket



BGA-484P SERIES (0.5mm PITCH)

Unit: mm

PART NO.	$M_{i,I}$	APPLIC	ABLE IC DIMENSION	ONS (REF.)	. 7	OUTSIDE	DIMENSIO	NS (REF.)	REMARKS
TANT NO.	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	A	B 00	C	ILWANKS
BGA-48(484P)-0.5-01	5×5	- 8	Depopulated	48		-11	1110	A COL	- N
BGA-57(484P)-0.5-14	5×5	9	Depopulated	57	LA.			1.	1.7
BGA-89(484P)-0.5-11	6×6	10	Depopulated	89		**		V.Cor	No.
BGA-96(484P)-0.5-26	6×6	11	Depopulated	96	7.4			00	M.r.
BGA-144(484P)-0.5-07	7×7	12	Fully Aray	144	W.	<		Jany.Co	TI
BGA-144(484P)-0.5-20	7×7	13	Fully Aray	144	1.7.			100	Mr.
BGA-132-(484P)-0.5-36	8×8	14	Depopulated	132	WT.			1007.0	WILL
BGA-161(484P)-0.5-40	8×8	15	Depopulated	161	0.5	40	00	15-1	Ohr.
BGA-220(484P)-0.5-**	9×9	16	Depopulated	220	0.5	40	38	15	
BGA-156(484P)-0.5-19	9×9	17	Depopulated	156				1.10	COM
BGA-277(484P)-0.5-08	10×10	18	Depopulated	277	- 11			-11 100 X	
BGA-240(484P)-0.5-10	10×10	19	Depopulated	240	Ohr	-XX		111.5	CO
BGA-223(484P)-0.5-13	11×11	20	Depopulated	223	1/20	1. 1.		-XX 100	
BGA-256(484P)-0.5-44	11×11	21	Depopulated	256	Co_{λ_1}	TV		1	V.Co
BGA-244(484P)-0.5-04	12×12	21	Depopulated	244		1.7		-TW.10	COM
BGA-340(484P)-0.5-**	12×12	22	Depopulated	340	V.Co	W			

⁻Max.12×12mm Package can be accommodated

BGA-784P SERIES (0.5mm PITCH)

PART NO.	100	APPLIC	ABLE IC DIMENSION	ONS (REF.)	001.	OUTSID	E DIMENSION	NS (REF.)	DEMARKO
rani Nu.	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	A	В	C	REMARKS
BGA-128(784P)-0.5-19	7×7	12	Depopulated	128	Ina	CON.	34	20	N. In
BGA-604(784P)-0.5-18	15×15	28	Depopulated	604	COOL		34	20	1007.
BGA-360(784P)-0.5-**	12×12	23	Depopulated	360	Too		- 41	-13	11.10
BGA-361(784P)-0.5-08	13×13	24	Depopulated	361	0.5	40	TW		1001
BGA-400(784P)-0.5-**	13×13	25	Depopulated	400	0.5	40	38	15 🕥	MM.
BGA-287(784P)-0.5-04	14×14	26	Depopulated	287	-110		30	15	-31 100
BGA-440(784P)-0.5-**	14×14	27	Depopulated	440	M. 7.		N.V.	*	11/1/11
BGA-385(784P)-0.5-06	15×15	28	Depopulated	385	-311		W.T.		100

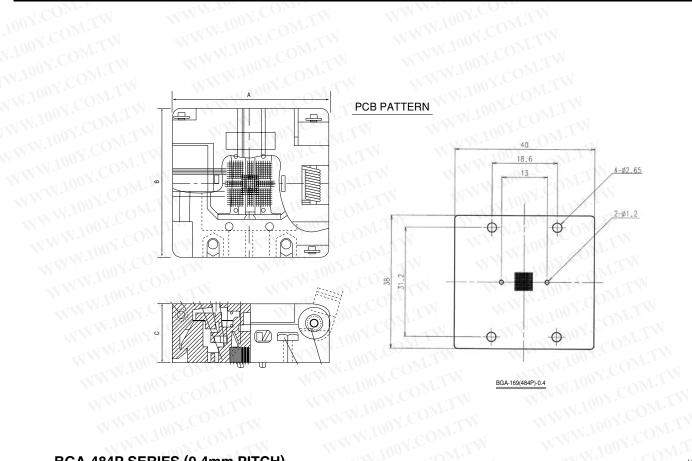
⁻ Max.16×16mm Package can be accommodated

- Max.16×16mm Packa	ge can be a	ccommoda	ated						
BGA-784BP SERI	ES (0.5m	m PITC	CH) — Вура	ass Type —					Unit : mm
PART NO.		APPLICA	ABLE IC DIMENSIO	ONS (REF.)	-737	OUTSIDE	DIMENSIO	NS (REF.)	DEMARKO
FANT NU.	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	A	В	C	REMARKS
BGA-344(784BP)-0.5-01	12×12	22×22	Depopulated	344	0.5	40	34	20.1	
BGA-121(784BP)-0.5-02	6×6	11×11	Fully Aray	121	V.5	70	04	20.1	

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WWW.100Y.COM.TW WWW.100Y.COM.TW Applicable IC/BGA·LGA

Clam Shell Surface Mount Type Socket



BGA-484P SERIES (0.4mm PITCH)

PART NO.	001.	APPLIC	ABLE IC DIMENSIC	ONS (REF.)	1011	OUTSIDI	DIMENSION	IS (REF.)	COMP
PANI NU.	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	Α	В	C, 00	REMARKS
GA-145(484P)-0.4-04	6×6	13	Fully Aray	145	0.4	40	34	20	A COM
GA-360(484P)-0.4-**	10×10	22	Depopulated	360	0.4	40	34	20	

⁻Max.10×10mm Package can be accommodated

PART NO.	ES (0.4mm PITCH) — Bypass Type — APPLICABLE IC DIMENSIONS (REF.)					OUTSID	E DIMENSIOI	NS (REF.)	DEMARKO
PANI NU.	BODY SIZE	GRID	ROW/ARRAY	LEADS NUMBER	PITCH	A	В	C	REMARKS
GA-141(484BP)-0.4-**	6×6	13	Depopulated	141	0.4	40	34	19.9	MW.